

CLAIMS

1. A method for patterning a surface (52) of a substrate (50) with an ink, the method comprising the steps of:

- 5 providing an elastomeric stamp (10) having a bulk surface (12) and at least one feature (14, 14') protruding from the bulk surface (12), the protruding feature (14, 14') having a contact surface (16, 16') and an edge (18, 18') extending from the contact surface (16, 16') to the bulk surface (12), the protruding feature (14, 14') and the bulk surface (12) carrying a barrier layer (20);
- 10 applying a solution of the ink and a solvent (30) to the barrier layer (20);
removing the solvent (30) from the barrier layer (20);
providing a first substrate (40) with a surface (42) having a higher affinity for the ink than the barrier layer (20);
- 15 contacting the contact surface (16, 16') of the protruding feature (14, 14') with the surface (42) of the first substrate (40);
transferring the ink from the contact surface (16, 16') of the protruding feature (14, 14') to the surface (42) of the first substrate (40);
removing the elastomeric stamp (10) from the surface (42) of the first substrate (40);
- 20 providing a second substrate (50) with a surface (52) having a higher affinity for the ink than the barrier layer (20);
contacting the contact surface (16, 16') of the protruding feature (14, 14') with the surface (52) of the second substrate (50); and
- 25 providing the surface (52) of the second substrate (50) with an ink pattern (60) by transferring the ink from the edge (18, 18') of the protruding feature (14, 14') to the surface (52) of the second substrate (50).

2. A method as claimed in claim 1, further comprising the step of removing
- 30 a part of the surface (52) of the second substrate (50), the part being defined by the ink pattern (60).

3. A method as claimed in claim 2, wherein the removing of the part of the surface (52) of the second substrate (50) comprises an etching step.